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TITLE: Direct interconnection method between bare chip
semiconductor integrated circuit and circuit substrate
pattern

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Basic Abstract Text - ABTX (2):

DETAILED DESCRIPTION - In the method, contrary to a conventional stud bump formed directly on the bare chip circuit, the bump(110) is formed on the pattern(51) of a circuit substrate(50) by using a solder ball. Therefore, the damage of the bare chip circuit is prevented and a conventional **UBM process is not required**. Next, the circuit substrate(50) having the bump(110) is coated with an anisotropic conductive paste(ACP) by using a syringe(120). Then, the bare chip(10) having an aluminum electrode(11) is mounted on the circuit substrate(50) while aligning the aluminum electrode(11) with the bump(110).

